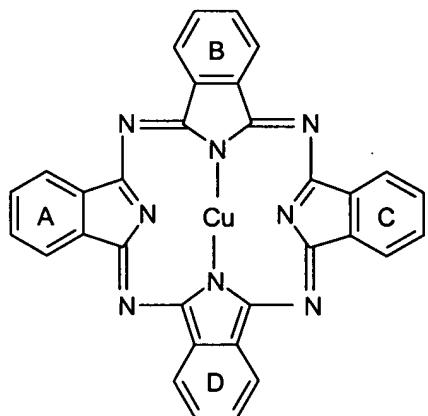


In the claims

1. (currently amended): A photosensitive resin composition comprising as a component (A) a green colorant of the formula



(1)

in which the rings A, B, C and D are substituted by hydroxy or by the moiety $-O-(CR_1R_2)_n-$  ,

wherein R₁ is hydrogen or C₁-C₄-Alkyl, R₂ is hydrogen or C₁-C₄-Alkyl, n is 0, 1, 2 or 3 and the ring E is unsubstituted or substituted by C₁-C₆alkyl, C₁-C₆alkoxy, hydroxy, NHCOR₃, NHSO₂R₄ or SO₂NHR₅, wherein R₃ is C₁-C₄-Alkyl or phenyl, R₄ is C₁-C₄-Alkyl or phenyl and R₅ is C₁-C₄-Alkyl or phenyl,

b) as a component (B) an alkali soluble reactive or unreactive oligomer or reactive or unreactive

polymer-(reactive or unreactive) ,

c) as a component (C) a polymerizable monomer,

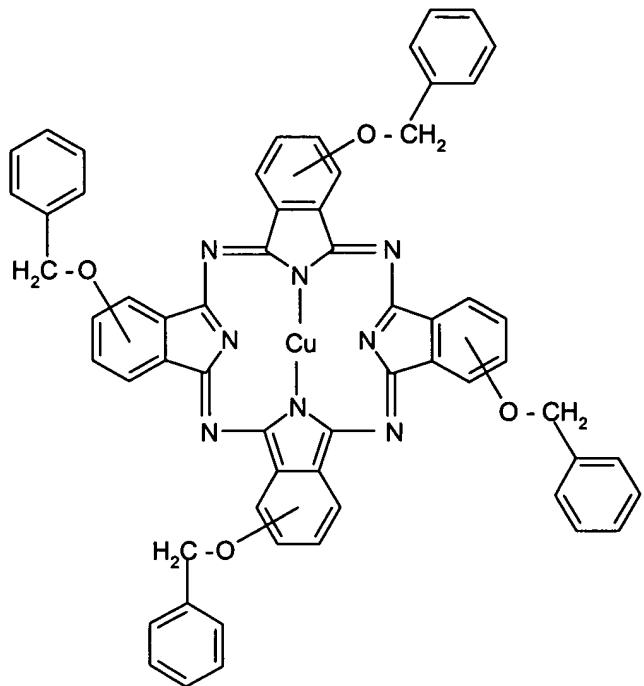
d) as a component (D) a photoinitiator,

e) as a component (E) an epoxy compound,

and also, if desired,

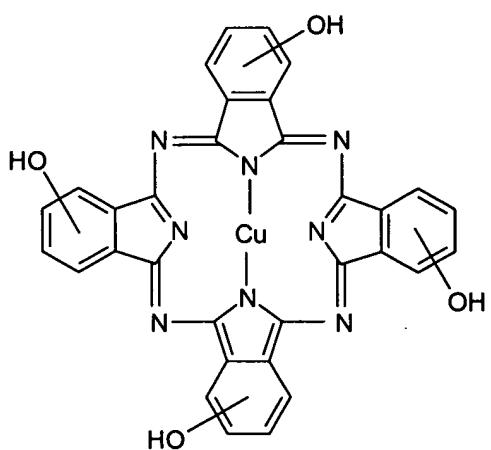
f) as a component (F) further additives.

2. (original): A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



(2).

3. (original): A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



(3).

4. (currently amended): Solder resist process, using the photosensitive resin composition according to any one of claims 1 to 3, which process comprises the steps of

(1) mixing the components (A) to (E) and if desired (F) according to claim 1,
(2) applying the resulting composition to the substrate ("coating of the substrate") to generate a coated substrate,

(3) evaporating of the solvent, if present, at a temperature between 80-90°C,
(4) exposing the coated substrate to irradiation through a negative mask or by a direct laser imaging,
(5) developing the irradiated sample by washing with aqueous alkaline solution and thereby removing the uncured areas,

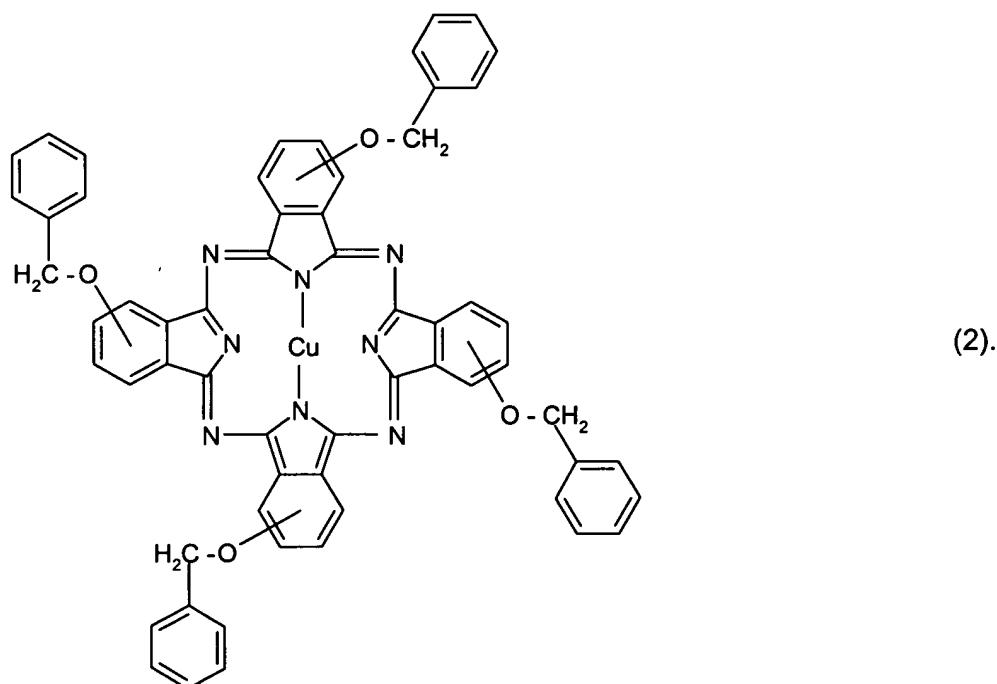
and

(6) thermally curing the sample at a temperature about 150°C, thereby initiating the crosslinking between the carboxylic acid and the epoxy component.

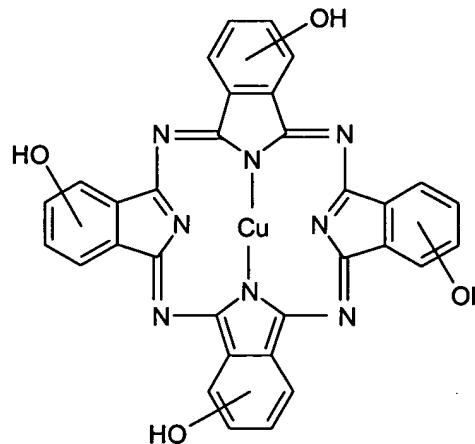
5. (original): Coated substrate obtained by the process according to claim 4.

6. (currently amended): Substrate coated with the photosensitive resin composition according to any of claim [[s]] 1 to 3.

7. (new): Solder resist process according to claim 4, wherein component (A) of step (1) is the colorant of formula



8. (new): Solder resist process according to claim 4, wherein component (A) of step (1)) is the colorant of formula



(3).

9. (new): Coated substrate obtained by the process according to claim 7.

10. (new): Coated substrate obtained by the process according to claim 8.

11. (new): Substrate coated with the photosensitive resin composition according to claim 2.

12. (new): Substrate coated with the photosensitive resin composition according to claim 3.

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